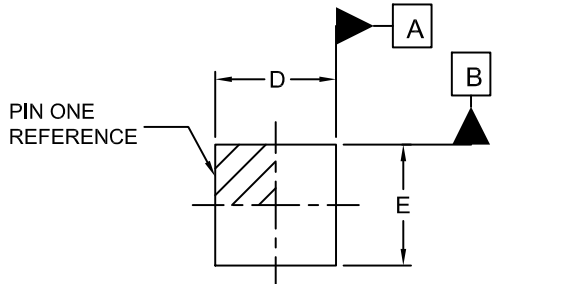


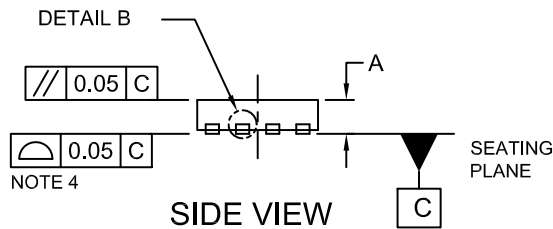


X2QFN12 1.6x1.6, 0.4P
CASE 722AG
ISSUE A

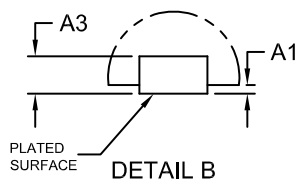
DATE 26 SEP 2017



TOP VIEW



SIDE VIEW

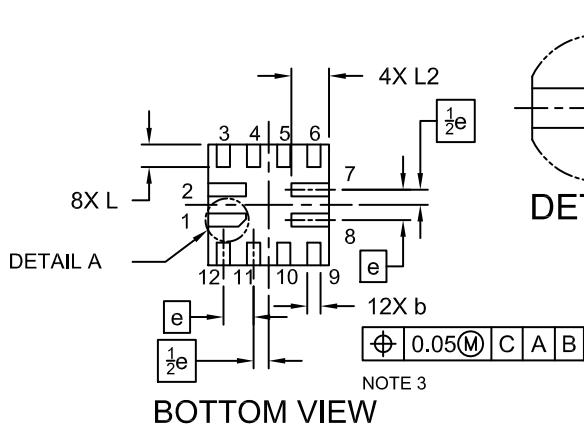


DETAIL B

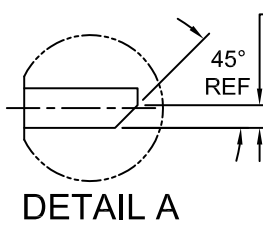
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO THE PLATED TERMINALS AND IS MEASURED BETWEEN 0.10 AND 0.20mm FROM THE TERMINAL TIP.
4. PROFILE APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

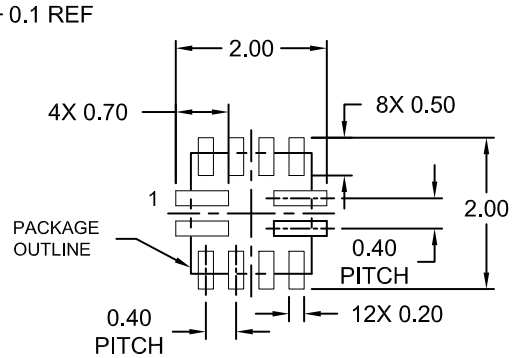
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.34	0.37	0.40
A1	--	--	0.05
A3	0.127 REF		
b	0.15	0.175	0.20
D	1.55	1.60	1.65
E	1.55	1.60	1.65
e	0.40 BSC		
L	0.25	0.30	0.35
L2	0.45	0.50	0.55



BOTTOM VIEW



DETAIL A



RECOMMENDED MOUNTING FOOTPRINT

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DESCRIPTION:	X2QFN12 1.6x1.6, 0.4P	PAGE 1 OF 1

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